Product Change Notification - GBNG-15KQFZ896

Date:

Product Category: Notification subject: Notification text: 11 Jul 2017

CCB 2971 Final Notice: Implement marking changes for virtually all Atmel products **PCN Status:** Final notification.

Microchip Parts Affected:

All virtually Atmel products.

Description of Change: Implement marking changes for virtually all Atmel products

Pre Change:

Atmel top marking format and with bottom marking.

Post Change:

Microchip top marking format, traceability code and without bottom mark.

Pre and Post Change Summary:

	Pre Change	Post Change
Top Mark	Atmel top marking format	Microchip top marking format and traceability code
Bottom Mark	With bottom marking	Without bottom marking
	See attached pre and	l post marking guidelines

Impacts to Data Sheet: Where applicable

Change Impact:

None

Reason for Change:

To improve manufacturability and traceability by standardizing marking format for virtually all Atmel products as part of the integration of Microchip and Atmel.

Change Implementation Status: In Progress

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Estimated First Ship Date:

September 01, 2017

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

		Ju	ly 20)17		>	S	epte	mbe	r 201	17
Workweek	27	28	29	30	31		35	36	37	38	39
Final PCN Issue Date		х									
Estimated Implementation Date							х				

Method to Identify Change:

Top marking and Traceability Code

Qualification Report: Not applicable

Revision History:

July 11, 2017: Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_GBNG-15KQFZ896_Part Marking Guideline_Part1.pdf PCN_GBNG-15KQFZ896_Part Marking Guideline_Part2.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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		Atmel			IIP
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
8	PDIP 300 MIL	$\begin{bmatrix} & & & & & & \\ & & & & & \\ & & & & & \\ & & & & & \\ \bullet & & & &$	Top Mark Line 1= Device Name Line 2 = Device Information Line 3 = Class Code, Date Code • = Pin 1 indicator OR Line 1= ATMEL, Date Code Line 2 = Device Name Line 3 = Device Information Bottom Mark Lot Number Country of Origin in the injector mold	Image: Constraint of the second s	Top MarkLine 1= Device Name, Class CodeLine 2 = Device InformationLine 3 = Lot Traceability• = Pin 1 indicatorORLine 1= ATML, Class Code, DateCodeLine 2 = Device Information,Country of OriginLine 3 = Lot TraceabilityBottom MarkNo bottom markCountry of Origin in injector mold
			Top Mark Line 1= ATML, Class Code, Date Code Line 2 = Device Information Line 3 = Lot Traceability Bottom Mark No bottom mark Country of Origin in injector mold	XXXXXXXXX XXXXXXXXXX XXXXXXXXXXX YYWWNNN YYWWNNN	Top Mark Line 1= Device Name, Class Code Line 2 = Device Information Line 3 = Lot Traceability • = Pin 1 indicator OR Line 1= ATML, Class Code, Date Code Line 2 = Device Information, Country of Origin Line 3 = Lot Traceability Bottom Mark
		$ \begin{array}{c} $	Top Mark Line 1= Atmel Logo, Date Code, MRL (if shown in ABI) Line 2 = Device Name Line 3 = Device Information ● ▲ = Pin 1 location Bottom Mark Line 1 = Country of Origin if not in injector mold Line 2 = Lot Traceability Country of Origin in injector mold		No bottom mark Country of Origin in injector mold Top Mark Line 1 = Atmel Logo, Die ID, Revision Line 2 = Device Name, Device Information Line 3 = Lot Traceability • = Pin 1 location OR Top Mark Line 1 = Atmel Logo, Device Information Line 2 = Device Name Line 3 = Lot Traceability Bottom Mark No bottom mark Country of Origin in injector mold

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.

Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Micro
14	PDIP 300 MIL	$ \begin{array}{c} & & & & & & & & & & & & & & & & & & &$	Top Mark Line 1= Atmel Logo, Date Code, MRL (if shown in ABI) Line 2 = Device Name, Device Information ● ▲ = Pin 1 location Bottom Mark Line 1 = Country of Origin if not in injector mold Line 2 = Lot Traceability Country of Origin in injector mold	
20	PDIP 300 MIL	$ \begin{array}{c} & & & & & & & & & & & & & & & & & & &$	 Top Mark Line 1= Atmel Logo, Date Code, MRL (if shown in ABI) Line 2 = Device Name, Device Information ▲ = Pin 1 location Bottom Mark Line 1 = Country of Origin if not in injector mold Line 2 = Lot Traceability Country of Origin in injector mold 	
24	PDIP300 MIL	$ \begin{array}{c} & & & & & & & & & & & & & & & & & & &$	 Top Mark Line 1= Atmel Logo, Date Code, MRL (if shown in ABI) Line 2 = Device Name, Device Information ▲ = Pin 1 location Bottom Mark Line 1 = Country of Origin if not in injector mold Line 2 = Lot Traceability Country of Origin in injector mold 	

Post-Change_Marking Guidelines (Microchip) Top Mark Line 1= Atmel Logo, Die ID, Revision Line 2 = Device Name, Device Information Line 3 = Lot Traceability = Pin 1 location Bottom Mark No bottom mark Country of Origin in injector mold Top Mark Line 1= Atmel Logo, Die ID, Revision Line 2 = Device Name, Device Information Line 3 = Lot Traceability = Pin 1 location OR Top Mark Line 1= Atmel Logo, Country of Origin Line 2 = Device Name, Device Information Line 2 = Device Name, Device Information Line 3 = Lot Traceability Bottom Mark No bottom mark Country of Origin in injector mold Top Mark Line 1= Atmel Logo, Country of Origin Line 3 = Lot Traceability Bottom Mark No bottom mark Country of Origin in injector mold Top Mark Line 1= Atmel Logo, Country of Origin Line 2 = Device Name, Device Information Line 3 = Lot Traceability = Pin 1 location Bottom Mark No bottom mark Country of Origin in injector mold Bottom Mark No bottom mark Country of Origin in injector mold		
Top Mark Line 1= Atmel Logo, Die ID, Revision Line 2 = Device Name, Device Information Line 3 = Lot TraceabilityIme 2 = Device Name, Device Information Line 3 = Lot TraceabilityEntern Mark No bottom mark Country of Origin in injector moldTop Mark Line 1= Atmel Logo, Die ID, Revision Line 2 = Device Name, Device Information Line 3 = Lot TraceabilityIme 2 = Device Name, Device Information Line 3 = Lot TraceabilityIme 1= Atmel Logo, Country of Origin Line 2 = Device Name, Device Information Line 3 = Lot TraceabilityBettom Mark No bottom mark Country of Origin in injector moldTop Mark Line 1 = Atmel Logo, Country of Origin Line 2 = Device Name, Device Information Line 3 = Lot TraceabilityBettom Mark No bottom mark Country of Origin in injector moldTop Mark Line 1 = Atmel Logo, Country of Origin Line 2 = Device Name, Device Information Line 3 = Lot TraceabilityBettom Mark No bottom mark Country of Origin in injector moldTop Mark Line 3 = Lot TraceabilityEnd 1 = Atmel Logo, Country of Origin Line 3 = Lot TraceabilityIme 3 = Lot Traceability </th <th>ochip)</th> <th>Post-Change_Marking Guidelines (Microchip)</th>	ochip)	Post-Change_Marking Guidelines (Microchip)
Top MarkLine 1= Atmel Logo, Die ID, RevisionLine 2 = Device Name, DeviceInformationLine 3 = Lot Traceability• = Pin 1 locationORTop MarkLine 1= Atmel Logo, Country of OriginLine 2 = Device Name, DeviceInformationLine 3 = Lot TraceabilityBottom MarkNo bottom mark Country of Origin in injector moldTop MarkLine 1= Atmel Logo, Country of 		 Top Mark Line 1= Atmel Logo, Die ID, Revision Line 2 = Device Name, Device Information Line 3 = Lot Traceability ● = Pin 1 location Bottom Mark No bottom mark Country of Origin in injector mold
Bottom Mark No bottom mark Country of Origin in injector moldTop Mark Line 1= Atmel Logo, Country of Origin Line 2 = Device Name, Device Information 		Top Mark Line 1= Atmel Logo, Die ID, Revision Line 2 = Device Name, Device Information Line 3 = Lot Traceability ● = Pin 1 location OR Top Mark Line 1= Atmel Logo, Country of Origin Line 2 = Device Name, Device Information Line 3 = Lot Traceability
Top Mark Line 1= Atmel Logo, Country of Origin Line 2 = Device Name, Device Information Line 3 = Lot Traceability ● = Pin 1 location Bottom Mark No bottom mark Country of Origin in injector mold		Bottom Mark No bottom mark Country of Origin in injector mold
		Top Mark Line 1= Atmel Logo, Country of Origin Line 2 = Device Name, Device Information Line 3 = Lot Traceability ● = Pin 1 location Bottom Mark No bottom mark Country of Origin in injector mold

		Atmel		MICRO	CHIP
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
28/32	PDIP 600 MIL		Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, MRL (if shown in ABI) ▲ = Pin 1 location Bottom Mark Line 1 = Country of Origin in injector mold, Lot Traceability		Top MarkLine 1= Atmel LogoLine 2 = Device NameLine 3 = Device Information, Die ID,RevisionLine 4 = Lot Traceabilityo = Pin 1 indicatorBottom MarkNo bottom mark
40	PDIP 600 MIL	$\begin{array}{c} \mathbf{A} \mathbf{A} \mathbf{A} \mathbf{A} \mathbf{A} \mathbf{A} \mathbf{A} A$	Top Mark Line 1= ATMEL Logo Line 2 = Device Name Line 3 = Date Code, Lot Traceability O = Pin 1 indicator Bottom Mark Line 1 = Country Code Line 2 = Lot Traceability	A A <td>Top Mark Line 1= ATMEL Logo Line 2 = Device Name Line 3 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark</td>	Top Mark Line 1= ATMEL Logo Line 2 = Device Name Line 3 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.

		Atmel		
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Micr
			Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, MRL (if shown in ABI) ▲ = Pin 1 location Bottom Mark Line 1 = Country of Origin if not in injector mold, Lot Traceability	
			Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, MRL (if shown in ABI) ▲ = Pin 1 location Bottom Mark Line 1 = Country of Origin if not in injector mold, Lot Traceability	
28	SPDIP		Top Mark Line 1= Atmel Logo, Date Code, MRL (if shown in ABI) Line 2 = Device Name, Device Information ● ▲ = Pin 1 location Bottom Mark Line 1 = Country of Origin if not in injector mold Line 2 = Lot Traceability Country of Origin in injector mold	

CROCHIP

ochip)	Post-Change_Marking Guidelines (Microchip)
	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Die ID, Revision Line 4 = Lot Traceability o = Pin 1 indicator
	Bottom Mark No bottom mark
<u>~ ~</u>	Top Mark Line 1 = Atmel Logo Line 2 = Device Information, Country of Origin Line 3 = Lot Traceability O = Pin 1 indicator
	Bottom Mark No Bottom Mark
	
	Top Mark Line 1= Atmel Logo, Die ID, Revision Line 2 = Device Name, Device Information Line 3 = Lot Traceability
	 Pin 1 location Bottom Mark No bottom mark Country of Origin in injector mold

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Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Mici
8	SOIJ	AA XXXXXXXXX XXXXXXXXX XXXXXXXXX XXXXXXXXX XXXXXXXXX XXXXXXXXX	Top Mark Line 1= ATMEL, Date Code Line 2 = Device Name Line 3 = Device Information O = Pin 1 indicator Bottom Mark Lot Number Country of Origin in the injector mold	
		A A XXXXXXXXX XXXXXXXXX AAAAAAA	Top Mark Line 1= ATML, Class Code, Date Code Line 2 = Truncation Code, Voltage Line 3 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark Country of Origin in injector mold	A A XXXXXXXXX XXXXXXXXXX XXXXXXXXXX YYWWNNNN YYWWNNNN
		ATMELYYWW# XXXXXX XXXX XXXX XXXX XXXX XXXX XX	Top Mark Line 1 = ATMEL, Date Code, MRL (if shown in ABI) Line 2 = Device Name Line 3 = Device Information $O \blacktriangle$ = Pin 1 indicator Bottom Mark Line 1 = Country of Origin if not in injector mold Country of Origin in injector mold Line 2 = Lot Traceability	ATMELXXX XXXXXX YYWWNNN O H H H H H H H H H

ochip)	Post-Change_Marking Guidelines (Microchip)
	Top Mark Line 1= ATML, Class Code, Date Code Line 2 = Truncation Code, Country of Origin Line 3 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark Country of Origin in injector mold
	Top Mark Line 1= ATML, Class Code, Date Code Line 2 = Truncation Code, Country of Origin Line 3 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark Country of Origin in injector mold
	 Top Mark Line 1 = ATMEL, Device Information Line 2 = Device Name Line 3 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark Country of Origin in injector mold

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		Atmel		
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Micro
8	SOIC	$ \begin{array}{c} $	Top Mark Line 1= Device Name Line 2 = Device Information Line 3 = Class Code, Date Code or Lot Traceability O = Pin 1 indicator Bottom Mark Lot Number Country of Origin in injector mold	
		A A XXXXXXXXX XXXXXXXXX XXXXXXXXX AAAAAAA	Top Mark Line 1= ATMEL, Date Code Line 2 = Device Name Line 3 = Device Information O = Pin 1 indicator OR Line 1= ATML, Class Code, Date Code Line 2 = Truncation Code Line 3 = Lot Traceability Bottom Mark No bottom mark Country of Origin in injector mold	
			Top Mark Line 1= Subcon Code Line 2 = Date Code O = Pin 1 indicator Bottom Mark No bottom mark Country of Origin in injector mold	

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rochip)	Post-Change_Marking Guidelines (Microchip)
	Top Mark Line 1= Device Name, Class Code Line 2 = Device Information Line 3 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark Country of Origin in injector mold
	Top Mark Line 1= ATML, Class Code, Date Code Line 2 = Device Information Line 3 = Lot Traceability OR Line 1= ATML, Class Code, Date Code Line 2 = Truncation Code, Country of Origin Line 3 = Lot Traceability Bottom Mark No bottom mark Country of Origin in injector mold
	Top Mark Line 1= Country of Origin Line 2 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark Country of Origin in injector mold

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		Atmel		
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Micro
		ATMELYYWW# XXXXXXX XXXX XXXX XXXX XXXX XXXX X	Top MarkLine 1 = ATMEL, Date Code, MRL(if shown in ABI)Line 2 = Device NameLine 3 = Device Information \mathbf{O} = Pin 1 indicatorBottom MarkLine 1 = Country of Origin if not ininjector moldCountry of Origin in injector moldLine 2 = AAAAAAA = LotTraceability	ATMELXXX XXXXXXXX YYWWNNN
14	SOIC 150 MIL	ATMELYYWW# XXXXXXX XXXX XXXX XXXX XXXX XXXX X	 Top Mark Line 1 = ATMEL, Date Code, MRL (if shown in ABI) Line 2 = Device Name Line 3 = Device Information O ▲ = Pin 1 indicator Bottom Mark XXXXX = Country of Origin if not in injector mold Country of Origin in injector mold AAAAAAA = Lot Traceability 	ATMELXXXXXX XXXXXX-XXX YYWWNNN HHHHHH HHHHHH HHHHHH HHHHHHH
16 / 20 / 24 / 28	SOIC 300 MIL		Top Mark Line 1= Atmel Logo, Date Code, MRL (if shown in ABI) Line 2 = Device Name, Device Information O = Pin 1 indicator Bottom Mark Line 1 = XXXXX Country of Origin in injector mold Line 2 = Lot Traceability	Image: A to be a total and the second se

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ochip)	Post-Change_Marking Guidelines (Microchip)
	Top MarkLine 1 = ATMEL, Device InformationLine 2 = Device NameLine 3 = Lot Traceability O = Pin 1 indicatorBottom MarkNo bottom markCountry of Origin in injector mold
	Top Mark Line 1 = ATMEL, Die ID, Revision
	Line 2 = Device Name, Device Information Line 3 = Lot Traceability \mathbf{O} = Pin 1 indicator
	Bottom Mark No bottom mark Country of Origin in injector mold
	Top Mark Line 1= Atmel Logo, Die ID, Revision Line 2 = Device Name, Device Information Line 3 = Lot Traceability O = Pin 1 indicator
	OR Top Mark Line 1= Atmel Logo, Country of Origin Line 2 = Device Name, Device Information Line 3 = Lot Traceability
	Bottom Mark No bottom mark Country of Origin in injector mold

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.

Pre-Change_Marking Guidelines (Atmel) Top Mark Line 1= Device Name Line 2 = Lot Traceability Line 3 = Device Information, Date Code • = Pin 1 indicator	Post-Change_Marking Diagram (Micro
Top Mark Line 1= Device Name Line 2 = Lot Traceability Line 3 = Device Information, Date Code • = Pin 1 indicator	XXXXXXXXX XXXXXXXXX XXXXXXXXX
Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability O = Pin 1 indicator	A A
Top Mark Line 1= Device Name Line 2 = Date Code, Lot Traceability O = Pin 1 indicator Bottom Mark Line 1 = Country Code Country of Origin in injector mold Line 2 = Lot Traceability	A A
	Bottom Mark Line 1 = Country Code Country of Origin in injector mold Line 2 = Lot Traceability

CROCHIP Post-Change_Marking Guidelines ochip) (Microchip) Top Mark Line 1= Device Name Line 2 = Lot Traceability Line 3 = Device Information, Date Code, Country of Origin • = Pin 1 indicator Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability O = Pin 1 indicator Top Mark Line 1= Device Name Line 2 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark Country of Origin in injector mold

Atmel				
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Micr
		AAAAAA YYWW AAAAAA HHHHHHHHHHHH AAAAAA	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Date Code, Lot Traceability O = Pin 1 indicator	AAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAA
			Bottom Mark Line 1 = Country Code Country of Origin in injector mold Line 2 = Lot Traceability	
28	SSOP 208 MIL	ATMEL XXXXXXXXXX YYWWX AAAAAA	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Date Code, Subcon Code Line 4 = Lot Traceability O = Pin 1 indicator	ATMEL XXXXXXXXXX YYWW YYWWNNN
			Bottom Mark No bottom mark Country of Origin in injector mold	

ICROCHIP		
icrochip)	Post-Change_Marking Guidelines (Microchip)	
	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Lot Traceability O = Pin 1 indicator	
	Bottom Mark No bottom mark Country of Origin in injector mold	
	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Date Code Line 4 = Lot Traceability O = Pin 1 indicator	
	Bottom Mark No bottom mark Country of Origin in injector mold	

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Atmel				
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Mic
8	TSSOP	XXXXX AA AA XXXXX AA AA	Top MarkLine 1= Class Code, Date CodeLine 2 = Truncation CodeO = Pin 1 indicatorORLine 1= Truncation CodeLine 2 = Device Name	
		AT * YWW XXXXXX AAAAAA	Bottom Mark Lot Traceability Country of Origin in injector mold Top Mark Line 1= AT, Class Code, Date Code Line 2 = Truncation Code Line 3 = Lot Traceability Bottom Mark No bottom mark Country of Origin in injector mold	CAT * YWW XXXXXXX YYWWNNN
		YMTC C	Top Mark Line 1= Subcon Code Line 2 = Lot Traceability Bottom Mark No bottom mark Country of Origin in injector mold	OXX YYWWNNN C
		XXXX XXXX XXXX XXXX XXXX XXXX XXXX XXXX XXXX	Top Mark Line 1= A, Date Code, MRL (if shown in ABI) Line 2 = Device Name (shortened) Line 3 = Device Information Bottom Mark No bottom mark Country of Origin in injector mold	XXXX XXXX WNNN
14	TSSOP	$\begin{array}{c} \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\$	 Top Mark Line 1 = AT, Date Code, MRL (if shown in ABI) Line 2 = Device Name Line 3 = Device Information O = Pin 1 indicator ▲ = Pin 1 location Bottom Mark Line 1 = Country of Origin if not in injector mold Country of Origin in injector mold Line 2 = Lot Traceability 	ATMELXXX XXXXXXX YYWWNNN O

ochip)	Post-Change_Marking Guidelines (Microchip)
	Top Mark Line 1= AT, Class Code, Date Code Line 2 = Truncation Code, Country of Origin Line 3 = Lot Traceability O = Pin 1 indicator
	Bottom Mark No bottom mark Country of Origin in injector mold
	Top Mark Line 1= AT, Class Code, Date Code Line 2 = Truncation Code, Country of Origin Line 3 = Lot Traceability O = Pin 1 indicator
	Bottom Mark No bottom mark Country of Origin in injector mold
	Top Mark Line 1= Country of Origin Line 2 = Lot Traceability
	Bottom Mark No bottom mark Country of Origin in injector mold
	Top Mark Line 1= Device Information Line 2 =Device Name (shortened) Line 3 = Lot Traceability
	Bottom Mark No bottom mark Country of Origin in injector mold
	Top Mark Line 1 = ATMEL, Device Information Line 2 = Device Name Line 3 = Lot Traceability O = Pin 1 indicator
	Bottom Mark No bottom mark Country of Origin in injector mold

Atmel					
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
16	TSSOP	XXXXXX XXXXXX-XXXX AAAAAA	Top MarkLine 1 = ATMEL Logo, Date Code,MRL (if shown in ABI)Line 2 = Device Name, DeviceInformationO = Pin 1 indicatorBottom MarkLine 1 = Country of Origin if not ininjector moldCountry of Origin in injector moldLine 2 = Lot Traceability	ATMELXXX XXXXXXXXX YYWWNNN UUUUUUUUUUUUUUUUUUUUUUUUUUUUUUU	Top Mark Line 1 = ATMEL, Device Information Line 2 = Device Name Line 3 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark Country of Origin in injector mold
20	TSSOP	XXXXXXX YYWW AAAAAAA UUUUUUUUUUUUUUUUUUUUUUUUUU	Top MarkLine 1= Device NameLine 2 = Date CodeLine 3 = Lot TraceabilityO = Pin 1 indicatorBottom MarkLine 1 = Country of Origin if not ininjector moldCountry of Origin in injector moldLine 2 = Lot Traceability	XXXXXXX YYWW YYWWNNNN OYYWWNNNN	Top Mark Line 1= Device Name Line 2 = Date Code Line 3 = Lot Traceability O = Pin 1 indicator Bottom Mark Country of Origin in injector mold
		XXXXXX XXXXXX-XXXX AAAAAA	Top MarkLine 1 = ATMEL Logo, Date Code,MRL (if shown in ABI)Line 2 = Device Name, DeviceInformationO = Pin 1 indicatorBottom MarkLine 1 = Country of Origin if not ininjector moldCountry of Origin in injector moldLine 2 = Lot Traceability	ATMELXXX XXXXXXXX YYWWNNN UUUUUUUUUUUUUUUUUUUUUUUUUUUUUUU	Top Mark Line 1 = ATMEL, Device Information Line 2 = Device Name Line 3 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark Country of Origin in injector mold

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.

		Atmel		
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Micro
20/24	TSSOP		Top Mark Line 1 = ATMEL Logo, Date Code, MRL (if shown in ABI) Line 2 = Device Name, Device Information 0 = Pin 1 indicator Bottom Mark Line 1 = Country of Origin if not in injector mold Country of Origin in injector mold Line 2 = Lot Traceability	XXXXXXXXX XXX-CC YYWWNNN
28/32	TSOP		Top Mark Line 1 = ATMEL Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, MRL (if shown in ABI) O = Pin 1 indicator ▲ = Pin 1 location Bottom Mark No bottom mark Country of Origin in injector mold	UTUTUTUTUTUTUTUTUTUTUTUTUTUTUTUTUTUTUT
	SOT-23	H H H XXXXX YMTC	Top Mark Line 1= Truncation Code, Class Code • = Pin 1 indicator Bottom Mark Lot Traceability (Year, Month, Trace Code)	A A A A A A A A A A A A A A A A A A A
		A A A XYMTC L	Top Mark Line 1= Lot Traceability (Year, Month, Trace Code) Bottom Mark No bottom mark	CC YY WWNNN

ochip)	Post-Change_Marking Guidelines (Microchip)
	Top Mark Line 1 = Device Name Line 2 = Device Information, Country Code Line 3 = Lot Traceability O = Pin 1 indicator
	Bottom Mark No bottom mark Country of Origin in injector mold
	Top Mark Line 1 = ATMEL Logo Line 2 = Device Name Line 3 = Device Information, Die ID, Revision Line 4 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark Country of Origin in injector mold
	Top Mark Line 1= Truncation Code, Subcon Code, Year Line 2 = Lot Traceability • = Pin 1 indicator Bottom Mark No bottom mark
	Top Mark Line 1= Country Code, Year Line 2 = Lot Traceability Bottom Mark No bottom mark

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.

Atmel				
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Mici
5	SOT-23		Top MarkLine 1= Truncation Code, DeviceInformation• = Pin 1 indicatorBottom MarkLot Traceability (Year, Month, Trace Code)	
			Top Mark Line 1= Truncation Code, Device Information Line 2 = Lot Traceability (Year, Month, Trace Code) Bottom Mark No bottom mark	
6	SOT-23		Top Mark Line 1= Device Name (shortened) o = Pin 1 indicator Bottom Mark Lot Traceability	XXXY WWNNN O
8	VFBGA	XXXX XYMTC	Top Mark Line 1= Truncation Code, Device Information Line 2 = Lot Traceability • = Pin 1 indicator	XXXX WWNNN
49	VFBGA 5X5 MM	● AT YYWW## XXXXXXXX XXXX-X AAAAAA	Top Mark Line 1= AT, Date Code, Die Revision, MRL (if shown in ABI) Line 2 = Device Name Line 3 = Device Information Line 4 = Lot Traceability • = Pin 1 indicator	• ATMEL XXXXXX XX-COO XXXXXX YYWWNNN

ochip)	Post-Change_Marking Guidelines (Microchip)
	Top Mark Line 1= Truncation Code, Device Information, Year Line 2 = Lot Traceability (Workweek, Lot Number) • = Pin 1 indicator
	Bottom Mark No bottom mark
	Top Mark Line 1= Truncation Code, Lot Traceability • = Pin 1 indicator Bottom Mark No bottom mark
	Top Mark Line 1= Device Name (shortened) Lie 2 = Lot Traceability o = Pin 1 indicator
	No bottom mark
	Top Mark Line 1= Truncation Code, Device Information, Year Line 2 = Lot Traceability • = Pin 1 indicator
	Top Mark Line 1= ATMEL Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Die ID, Revision Line 5 = Lot Traceability • = Pin 1 indicator

Atmel				MICROCHIP	
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
96	VFBGA 6X6 MM	LIMES XXXXXXXXXX YYWWX X AAAAAA	Top Mark Line 1= LIMES Line 2 = Device Name Line 3 = Date Code, Subcon Code, Design Revision Line 4 = Lot Traceability ● = Pin 1 indicator	LIMES XXXXXXXXX YYWW X YYWWNNN	Top Mark Line 1= LIMES Line 2 = Device Name Line 3 = Date Code, Design Revision Line 4 = Lot Traceability ● = Pin 1 indicator
100	VFBGA 7X7 MM	∕ltmel XXXXXXXXXXX XXX YYWWX X AAAAAA <u>ARM</u> ●	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM • = Pin 1 indicator	Atmel XXXXXXXXXXX XXX YYWW X YYWWNNN ARM ●	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator
		∕tmel XXXXXXXXXXX XXX YYWWX X YYWWNNN <u>ARM</u>	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM • = Pin 1 indicator	Atmel XXXXXXXXXXXX XXX YYWW X YYWWNNN ARM	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator
		• S XXXXXXXXXX XXXXXXX YYWWX X AAAAAA ARM	Top Mark Line 1= Microchip Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM • = Pin 1 indicator	• S XXXXXXXXXX XXXXXXX YYWW X YYWWNNN ARM	Top Mark Line 1= Microchip Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator

		Atmel		Microc	HIP
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
		• • • • • • • • • • • • • • • • • • •	Top Mark Line 1= Atmel Logo, Date Code, MRL (if shown in ABI) Line 2 = Device Name Line 3 = Device Information Line 3 = Country of Assembly Line 4 = Lot Traceability Line 5 = Die ID, Revision • = Pin 1 indicator	• XXXXXXX X-COO XXXXXX YYWWNNN	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Die ID, Revision Line 5 = Lot Traceability • = Pin 1 indicator
40	TFBGA 4X4 MM	• XXXXXX XXXXXX AAAAAA X YYWW	Top Mark Line 1= Device Name Line 2 = Device Information Line 3 = Lot Traceability Line 4 = Subcon Code, Date Code • = Pin 1 indicator	• XXXXXX XXXXXX YYWWNNN CC YYWW	Top Mark Line 1= Device Name Line 2 = Lot Traceability Line 3 = Country of Origin, Date Code • = Pin 1 indicator
256	TFBGA 8X8 MM	Atmel XXXXXXXXXX XX YYWWX X AAAAAA <u>ARM</u>	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM • = Pin 1 indicator	Atmel XXXXXXXXXX XX YYWW X YYWWNNN ARM	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM • = Pin 1 indicator
100	TFBGA 9X9 MM	Atmel XXXXXXXXXXXXX XXXXXX YYWWX X AAAAAA <u>ARM</u>	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator	∕tmel XXXXXXXXXXXX XXXXXX YYWW X YYWWNNN <u>ARM</u> ●	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM • = Pin 1 indicator

Atmel			MICROCHIP		
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
		XXXXXXXXXX XXXXXXX YYWWX X AAAAAA ARM	Top Mark Line 1= Microchip Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator	• XXXXXXXXXX XXXXXX YYWW X YYWWNNN ARM	Top Mark Line 1= Microchip Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM • = Pin 1 indicator
		YYWW## XXXXXXXX XXXXX XXXXXX AAAAAAA XXXXXXX	Top Mark Line 1= Atmel Logo, Date Code, MRL (if shown in ABI) Line 2 = Device Name Line 3 = Device Information Line 3 = Country of Assembly Line 4 = Lot Traceability Line 5 = Die ID, Revision • = Pin 1 indicator	• MEL XXXXXXX XXX-COO XXXXXX YYWWNNN	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Die ID, Revision Line 5 = Lot Traceability • = Pin 1 indicator
144	TFBGA 10X10 MM	MICROCHIP XXXXXXXXXX XXXXXX YYWWX X AAAAAA <u>ARM</u>	Top MarkLine 1= Microchip LogoLine 2 = MicrochipLine 3 = Device NameLine 4 = Device InformationLine 5 = Date Code, Subcon Code,Design RevisionLine 6 = Lot Traceability, ARM• = Pin 1 indicator	MICROCHIP XXXXXXXXXXX XXXXXX YYWW X YYWWNNN ARM	Top Mark Line 1= Microchip Logo Line 2 = Microchip Line 3 = Device Name Line 4 = Device Information Line 5 = Date Code, Design Revision Line 6 = Lot Traceability, ARM • = Pin 1 indicator
		∕ltmel XXXXXXXXXXXX XXXXXXXXXX YYWWX X AAAAAA <u>ARM</u> ●	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM • = Pin 1 indicator	✓tmel XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM • = Pin 1 indicator



CROCHI	CROCHIP				
ochip)	Post-Change_Marking Guidelines (Microchip)				
	Top Mark Line 1= Microchip Logo Line 2 = Microchip Line 3 = Device Name Line 4 = Device Information Line 5 = Date Code, Design Revision Line 6 = Lot Traceability, ARM • = Pin 1 indicator				
	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM • = Pin 1 indicator				
	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM • = Pin 1 indicator				

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.

Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Mic
144	TFBGA 12X12 MM	XXXXXXXX XXXX XXXX YYWWX X AAAAAA ARM	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM • = Pin 1 indicator	XXXXXXXX XXXX XXXX YYWW X YYWWNNN ARM
324	TFBGA 12X12 MM	∕ltmel XXXXXXXXXX XXXXXXX YYWWX X AAAAAA <u>ARM</u>	Top MarkLine 1= Atmel LogoLine 2 = Device NameLine 3 = Device InformationLine 4 = Date Code, SubconCode, Design RevisionLine 5 = Lot Traceability, ARM• = Pin 1 indicator	✓Itmel XXXXXXXXXXX XXXXXXXXX YYWW X YYWWNNN ARM
361	TFBGA 16X16 MM	Atmel XXXXXXXXXX XX YYWWX X AAAAAA ARM	Top MarkLine 1= Atmel LogoLine 2 = Device NameLine 3 = Device InformationLine 4 = Date Code, SubconCode, Design RevisionLine 5 = Lot Traceability, ARM• = Pin 1 indicator	✓tmel XXXXXXXXXX XX YYWW X YYWWNNN ARM
144	LFBGA 10X10 MM	∕ltmel XXXXXXXXXXXX XXXXXXXXXX YYWWX X AAAAAA <u>ARM</u> ●	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM • = Pin 1 indicator	✓Itmel XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX

ICROCHIP Post-Change_Marking Guidelines rochip) (Microchip) Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM • = Pin 1 indicator Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM • = Pin 1 indicator Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM • = Pin 1 indicator Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM • = Pin 1 indicator

Atmel				MICROCHIP		
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)	
289	LFBGA 14X14 MM	Atmel XXXXXXXXX XXXXXX YYWWX X AAAAAA <u>ARM</u>	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator	∕ltmel XXXXXXXXXX XXXXXX YYWW X YYWWNNN <u>ARM</u>	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM • = Pin 1 indicator	
		∕tmel XXXXXXXXXX XXXXXX YYWWX-X X AAAAAA <u>ARM</u>	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator	Atmel XXXXXXXXXX XXXXXXX YYWW-X X YYWWNNN <u>ARM</u> ●	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM • = Pin 1 indicator	
217	LFBGA 15X15 MM	✓tmel ✓tmel XXXXXXXXXXX XXX XXX XXX YYWWX X AAAAAA ARM OR OR	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM • = Pin 1 indicator	✓tmel XXXXXXXXXXXX XXX XXX YYWW YYWW YYWWNNN ARM OR	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM • = Pin 1 indicator	
256	LFBGA 15X15 MM	✓tmel XXXXXXXXX XXXXXXXX XXXXXXXX XXXXXXXX YYWWX-X AAAAAA ARM OR	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM • = Pin 1 indicator	Atmel XXXXXXXXX XXXXXXX YYWW-X X YYWWNNN ARM OR	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM • = Pin 1 indicator	

Atmel				MICROCHIP			
Lead/Pin/ Bump Count	Package Description	Pre-Change_M	arking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_	_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
		XXXXXXXXXX XX YYWWX X AAAAAA ARM	Atmel XXXXXXXXXX XXXXXXX XXXXXX YYWWX X AAAAAA AAAA ARM AAAAAA AAAAAAAAAA	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator	XXXXXXXXX XX YYWW X YYWWNNN ARM	• Atmel XXXXXXXXXX XXXXXX YYWW X YYWW X YYWWNNN ARM	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM • = Pin 1 indicator
				Top Mark			
		Atmel XXXXXXXX		Line 1= Atmel Logo Line 2 = Device Name Line 3 = Date Code, Subcon Code, Design Revision	Atmel XXXXXXXX		Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Date Code, Design Revision
		YYWWX X AAAAAA <u>ARM</u>		• = Pin 1 indicator	YYWW X YYWWNNN ARM		 Line 4 = Lot Traceability, ARM Pin 1 indicator
15	UEBGA 3X3 MM			Top Mark			Top Mark
		• XXX		Line 1= Device Name (shortened) Line 2 = Device Type Code Line 3 = Lot Traceability • = Pin 1 indicator	• XXXX		Line 1= Device Name (shortened) Line 2 = Device Information, Country of Origin Line 3 = Lot Traceability
		XXX			XXXX		• = Pin 1 indicator
		YZZ			YWWNNN		
32	UFBGA 4X4 MM			Top Mark Line 1= A, Date Code, MRL (if			Top Mark Line 1= Atmel
		●XYWW#		shown in ABI) Line 2 = Device Name Line 3 = Device Information, Die	•ATMEL		Line 2 = Device Name Line 3 = Device Information, Country of Origin
		XXXXX		Revision Line 4 = Lot Traceability • = Pin 1 indicator	XXXX VVVV		Line 4 = Lot Traceability • = Pin 1 indicator
					YTATIAININN		
					T 0.000T4T4TATA		

Atmel			MICROCHIP		
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
49	UFBGA 5X5 MM	• AT YYWW## XXXXXXXXX XXXX-X AAAAAA	Top Mark Line 1= AT, Date Code, Die Revision, MRL (if shown in ABI) Line 2 = Device Name Line 3 = Device Information Line 4 = Lot Traceability • = Pin 1 indicator	• ATMEL XXXXXX XX-COO XXXXXX YYWWNNN	Top MarkLine 1= ATMELLine 2 = Device NameLine 3 = Device Information,Country of OriginLine 4 = Die ID, RevisionLine 5 = Lot Traceability● = Pin 1 indicator
144	UFBGA 6X6 MM	<mark>∕ltmel</mark> XXXXXXXXXXX XXX YYWWXX AAAAAA <u>ARM</u>	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM • = Pin 1 indicator	Atmel XXXXXXXXXXX XXX YYWW X YYWWNNN ARM	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM • = Pin 1 indicator
		•	Top Mark Line 1= Microchip Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM • = Pin 1 indicator	• S XXXXXXXXXX XXXXXXX YYWW X YYWWNNN ARM	Top Mark Line 1= Microchip Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM • = Pin 1 indicator
36	WLGA 6.5X3.5 MM	• AT XXXXX XXXXYWWX AAAAAA	Top Mark Line 1= AT, Device Name (shortened) Line 2 = Device Information, Date Code, Die Revision Line 3 = Lot Traceability • = Pin 1 indicator	• AT XXXXX XXX-COO YYWWNNN	Top Mark Line 1= AT, Device Name (shortened) Line 2 = Device Information, Country of Origin Line 3 = Lot Traceability • = Pin 1 indicator

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.

Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Micr
4	WLCSP	● C YTC	Top Mark Line 1= Subcon Code Line 2 = Lot Traceability • = Pin 1 indicator	●₩W NNN
8	WLCSP	●CU XXX YTC	Top Mark Line 1= Device Information Line 2 = Truncation Code Line 3 = Lot Traceability • = Pin 1 indicator	•XX XXX NNN
		ATML*YWW XXXXXXXX AAAAAA	Top Mark Line 1= ATML, Class Code, Date Code Line 2 = Truncation Code Line 3 = Lot Traceability • = Pin 1 indicator	ATML*YWW XXXXXXXX YYWWNNN
31	WLCSP	• XXXXXXXX XXXXXXXX AAAAAA.## X YYWW	Top Mark Line 1= Device Name Line 2 = Device Information Line 3 = Lot Traceability Line 4 = Date Code • = Pin 1 indicator	• XXXXXXXX XXXXXXXX YYWWNNN CC YYWW

CROCHIP Post-Change_Marking Guidelines rochip) (Microchip) Top Mark Line 1= Workweek Line 2 = Lot Traceability • = Pin 1 indicator Top Mark Line 1= Country of Origin Line 2 = Truncation Code Line 3 = Lot Traceability • = Pin 1 indicator Top Mark Line 1= ATML, Class Code, Date Code Line 2 = Truncation Code, Country of Origin Line 3 = Lot Traceability • = Pin 1 indicator Top Mark Line 1= Device Name Line 2 = Device Information Line 3 = Lot Traceability Line 4 = Country of Origin, Date Code • = Pin 1 indicator

		Atmel			
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
54	WLCSP	XXXXXXXX XXXXXXXX AAAAAA.##	Top Mark Line 1= Device Name Line 2 = Date Code Line 3 = Lot Traceability • = Pin 1 indicator	XXXXXXXX YYWWNNN CC YYWW	Top Mark Line 1= Device Name Line 2 = Lot Traceability Line 3 = Country of Origin, Date Code • = Pin 1 indicator
49 / 64	WLCSP	▲tmel XXXXXXXXXXX XX YYWWX X AAAAAA ARM	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator	◆ /tmel XXXXXXXXXXX XX XX YYWW X YYWW X YYWWNNN ARM	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM • = Pin 1 indicator
20	VQFN 3X3 MM	• XXX XXX YZZ	Top Mark Line 1= Device Name (shortened) Line 2 = Device type code / Class code / Die Revision / Assembly location code Line 3 = Lot Traceability • = Pin 1 indicator	• XXX XXX WNNN	Top Mark Line 1= Device Name (shortened) Line 2 = Device type code / Class code, Die Revision / Assembly location code Line 3 = Lot Traceability • = Pin 1 indicator Bottom Mark No bottom mark
24/28	VQFN 4X4 MM	• XYYWW# XXXXXXX XXXXXXX AAAAAA OR XYWW# XXYWW# XXXXXX XXXXXX AAAAAAA OR	Top Mark Line 1= A, Date Code, MRL (if shown in ABI) Line 2 = Device Name Line 3 = Device Information Line 4 = Lot Traceability • = Pin 1 indicator	ATMEL XXXXX XXXX-COO YYWWNNN OR	Top Mark Line 1= ATMEL Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Lot Traceability • = Pin 1 indicator

Atmel					
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
		● ATMEL XXXXXXXX XXXX-X YYWW AAAAAA	Top Mark Line 1= ATMEL Line 2 = Device Name Line 3 = Class, Die Revision, Assembly Location Code Line 4 = Date Code Line 5 = Lot Traceability • = Pin 1 indicator	• XXXXXXX XX-COO YYWWNNN	Top Mark Line 1= ATMEL Line 2 = Device Name Line 3 = Class, Die Revision, Country of Origin Line 4 = Lot Traceability • = Pin 1 indicator
		• ATMEL XXXXXXXX XXXXYYWW# XXXX-X XXXXXX AAAAAA	Top Mark Line 1= ATMEL Line 2 = Device Name Line 3 = Device Information, Date Code, MRL (if shown in ABI) Line 4 = Class, Assembly Location Code Line 5 = Die ID, Revision Line 6 = Lot Traceability • = Pin 1 indicator	• XXXXXXX XXX-COO XXXXXXX YYWWNNN	Top Mark Line 1= ATMEL Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Die ID, Revision Line 5 = Lot Traceability • = Pin 1 indicator
24 / 32 / 40 / 44 / 48	VQFN 5X5 MM	XXXXXX XXXXXX AAAAAA X YYWW	Top Mark Line 1= Device Name Line 2 = Device Information Line 3 = Lot Traceability Line 4 = Subcon Code, Date Code • = Pin 1 indicator	• XXXXXX XXXXXX YYWWNNN CC YYWW	Top Mark Line 1= Device Name Line 2 = Device Information Line 3 = Lot Traceability Line 4 = Country of Origin, Date Code • = Pin 1 indicator
		• XXXXXXXX AAAAAA.# X YYWW	Top Mark Line 1= Device Name Line 2 = Lot Traceability Line 3 = Date Code	• XXXXXXXX YYWWNNN CCYYWW	Top Mark Line 1= Device Name Line 2 = Lot Traceability Line 3 = Country of Origin, Date Code
		 ATMEL XXXXXXXXX XXXXXXXX XXXXXXX XXXXXXX XXXX XXX XXXX XX	Top Mark Line 1= ATMEL Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, MRL (if shown in ABI) Line 5 = Lot Traceability • = Pin 1 indicator	 ATMEL XXXXXX XX-COO XXXXXX YYWWNNN OR 	Top Mark Line 1= ATMEL Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Die ID, Revision Line 5 = Lot Traceability • = Pin 1 indicator

Atmel				MICROCHIP	
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
		• ATMEL XXXXXXXXX XXXX-X YYWW AAAAAA	Top Mark Line 1= ATMEL Line 2 = Device Name Line 3 = Device Information, MRL (if shown in ABI) Line 4 = Date Code Line 5 = Lot Traceability ● = Pin 1 indicator	• ATMEL XXXXXXX XX-COO YYWWNNN	Top Mark Line 1= ATMEL Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Lot Traceability • = Pin 1 indicator
40	VQFN 6X6 MM	• ATMEL XXXXXXXX XXXX-X YYWW AAAAAA	Top Mark Line 1= ATMEL Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code Line 5 = Lot Traceability • = Pin 1 indicator	• XXXXXXX XX-COO YYWWNNN	Top Mark Line 1= ATMEL Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Lot Traceability • = Pin 1 indicator
48	VQFN 6X6 MM	✓Itmel XXXXXXX XXXXXX YYWWX X AAAAAA ARM	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM • = Pin 1 indicator	Atmel XXXXXXX XXXXXXX YWW X YYWWNNN ARM	Top MarkLine 1= Atmel LogoLine 2 = Device NameLine 3 = Device InformationLine 4 = Date Code, DesignRevisionLine 5 = Lot Traceability, ARM• = Pin 1 indicator
		● ATMEL XXXXXXXX XXXX-X YYWW AAAAAA	Top Mark Line 1= ATMEL Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code Line 5 = Lot Traceability ● = Pin 1 indicator	• ATMEL XXXXXXX XX-COO YYWWNNN	Top Mark Line 1= ATMEL Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Lot Traceability • = Pin 1 indicator

Atmel				MICROCHIP	
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
44 / 64	VQFN 7X7 MM	ATMEL XXXXXXXX XXXXYYWW# XXXX-X XXXXXX AAAAAA	Top Mark Line 1= ATMEL Line 2 = Device Name Line 3 = Device Information, Date Code, MRL (if shown in ABI) Line 4 = Country of Assembly, Assembly Location Code Line 5 = Die ID, Revision Line 6 = Lot Traceability • = Pin 1 indicator	• XXXXXXX XXX-COO XXXXXX YYWWNNN	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Die ID, Revision Line 5 = Lot Traceability • = Pin 1 indicator Bottom Mark No bottom mark
48	VQFN 7X7 MM	Atmel XXXXXXXXX XX YYWWX X AAAAAA <u>ARM</u> ●	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM • = Pin 1 indicator	Atmel XXXXXXXXX XX YYWW X YYWW X YYWWNNN ARM	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM • = Pin 1 indicator
64	VQFN 7.5X7.5 MM	LIMES XXXXXXXXXX YYWWX X AAAAAA	Top Mark Line 1= LIMES Line 2 = Device Name Line 3 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability ● = Pin 1 indicator	LIMES XXXXXXXXXX YYWW X YYWWNNN	Top Mark Line 1= LIMES Line 2 = Device Name Line 3 = Date Code, Design Revision Line 5 = Lot Traceability • = Pin 1 indicator
		XXXXXXXXXXX YYWWX X AAAAAA	Top Mark Line 1= Device Name Line 2 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability • = Pin 1 indicator	XXXXXXXXXXX YYWW X YYWWNNN	Top Mark Line 1= Device Name Line 2 = Date Code, Design Revision Line 5 = Lot Traceability • = Pin 1 indicator

Atmel			MICROCHIP		
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
		Atmel XXXXXXXXXX XX YYWWX X AAAAAA <u>ARM</u>	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM • = Pin 1 indicator	Atmel XXXXXXXXXX XX YYWW X YYWWNNN <u>ARM</u> ●	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM • = Pin 1 indicator
64	VQFN 9X9 MM	Atmel XXXXXXXXXXX XX YYWWX X AAAAAA <u>ARM</u> ●	Top MarkLine 1= Atmel LogoLine 2 = Device NameLine 3 = Device InformationLine 4 = Date Code, Subcon Code,Design RevisionLine 5 = Lot Traceability, ARM• = Pin 1 indicator	Atmel XXXXXXXXXXX XX YYWW X YYWWNNN <u>ARM</u> ●	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM • = Pin 1 indicator
		• ATMEL XXXXXXXX XXXXYYWW# XXXX-X XXXXXX AAAAAA	Top Mark Line 1= ATMEL Line 2 = Device Name Line 3 = Device Information, Date Code, MRL (if shown in ABI) Line 4 = Country of Assembly, Assembly Location Code Line 5 = Die ID, Revision Line 6 = Lot Traceability • = Pin 1 indicator	• XXXXXXX XXX-COO XXXXXX YYWWNNN	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Die ID, Revision Line 5 = Lot Traceability • = Pin 1 indicator Bottom Mark No bottom mark
		• ATMEL XXXXXXXXX XXXX-X YYWW AAAAAA	Top Mark Line 1= ATMEL Line 2 = Device Name Line 3 = Class, Die Revision, Assembly Location Code Line 4 = Date Code Line 5 = Lot Traceability • = Pin 1 indicator	• ATMEL XXXXXXX XX-COO YYWWNNN	Top Mark Line 1= ATMEL Line 2 = Device Name Line 3 = Class, Die Revision, Country of Origin Line 4 = Lot Traceability • = Pin 1 indicator

Atmel				MICROCI	HIP
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
20	WQFN 4X4 MM	• XYYWW# XXXXXX XXXXXX AAAAAA	Top Mark Line 1= A, Date Code, MRL (if shown in ABI) Line 2 = Device Name (shortened) Line 3 = Device Information Line 4 = Lot Traceability • = Pin 1 indicator	• ATMEL XXXXX XXXX-COO YYWWNNN	Top Mark Line 1= ATMEL Line 2 = Device Name (shortened) Line 3 = Device Information, Country of Origin Line 4 = Lot Traceability • = Pin 1 indicator
8	UDQFN 2X2 MM	• XXX XXX YZZ	Top Mark Line 1= Device Name (shortened) Line 2 = Device type code / Class code / Die Revision / Assembly location code Line 3 = Lot Traceability • = Pin 1 indicator	• XXX XXX NNN	Top Mark Line 1= Device Name (shortened) Line 2 = Device type code / Class code, Die Revision / Assembly location code Line 3 = Lot Traceability • = Pin 1 indicator
8	UDFN 2X3 MM	XXX XXX YTC	Top Mark Line 1= Truncation Code Line 2 = Device Information Line 3 = Lot Traceability • = Pin 1 indicator	XXX XXX NNN	Top Mark Line 1= Truncation Code Line 2 = Device Information Line 3 = Lot Traceability • = Pin 1 indicator
		YM TC C	Top Mark Line 1= Year, Month Line 2 = Lot Traceability Line 3 = Subcon Code	YWW NNN CC	Top Mark Line 1= Date Code Line 2 = Lot Traceability Line 3 = Country Code
8	XDFN / UDFN	C YM TC	Top Mark Line 1= Subcon Code Line 2 = Year, Month Line 3 = Lot Traceability	CC YWW NNN	Top Mark Line 1= Country of Origin Line 2 = Date Code Line 3 = Lot Traceability

	Atmel				
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
8	UDFN 6X5 MM	XXXXXXXX XXXXXXXX •AAAAAA	Top Mark Line 1= ATML, Class Code, Date Code Line 2 = Truncation Code Line 3 = Lot Traceability ● = Pin 1 indicator	XXXXXXXX XXXXXXXX •YYWWNNN	Top Mark Line 1= ATML, Class Code, Date Code Line 2 = Truncation Code Line 3 = Lot Traceability ● = Pin 1 indicator
10	VDFN 3X3 MM	• XXX XXX YZZ	Top Mark Line 1= Device Name (shortened) Line 2 = Device type code / Class code / Die Revision / Assembly location code Line 3 = Lot Traceability • = Pin 1 indicator	• XXX XXX WNNN	Top Mark Line 1= Device Name (shortened) Line 2 = Device type code / Class code, Die Revision / Assembly location code Line 3 = Lot Traceability • = Pin 1 indicator Bottom Mark No bottom mark
2	XSFN (DFN 5X3.5 MM)	XXXXX XXXXX YMTC	Top Mark Line 1= ATML Line 2 = Truncation Code, Device Information Line 3 = Lot Traceability • = Pin 1 indicator	XXXXX XXXXX WWNNN	Top Mark Line 1= ATML Line 2 = Truncation Code, Device Information, Year Line 3 = Lot Traceability • = Pin 1 indicator
3	LAB (DFN 2.5X6.5 MM)	C YM TC	Top Mark Line 1= Subcon Code Line 2 = Year, Month Line 3 = Trace Code ● = Pin 1 indicator	● YWW NNN	Top Mark Line 1= Country of Origin Line 2 = Date Code Line 3 = Lot Traceability • = Pin 1 indicator

Atmel				MICROCHIP		
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)	
20	PLCC	XXXXXXXX AAAAAA XXXXXXXXX	Top Mark Line 1= Device Name Line 2 = Lot Traceability Line 3 = Device Information, Date Code • = Pin 1 indicator	XXXXXXXXX XXXXXXXXX YYWWNNN CC	Top Mark Line 1= Device Name Line 2 = Device Information, Date Code Line 3 = Lot Traceability Line 4 = Country of Origin • = Pin 1 indicator	
		XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Date Code, MRL (if shown in ABI) ▲ = Pin 1 location Bottom Mark Line 1 = Country of Origin if not in injector mold Country of Origin in injector mold Line 2 = Lot Traceability	XXXXXXXXXX XXXX-COO YYWWNNN	Top MarkLine 1= Atmel LogoLine 2 = Device NameLine 3 = Device Information,Country of OriginLine 4 = Lot Traceability• = Pin 1 indicatorBottom MarkNo bottom markCountry of Origin in injector mold	
28	PLCC		Top MarkLine 1= Atmel LogoLine 2 = Device NameLine 3 = Device InformationLine 4 = Date Code, LotTraceabilityO = Pin 1 indicatorBottom MarkLine 1 = Country CodeCountry of Origin in injector moldLine 2 = Lot Traceability	XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top MarkLine 1= Atmel LogoLine 2 = Device NameLine 3 = Device InformationLine 4 = Lot TraceabilityO = Pin 1 indicatorBottom MarkNo bottom markCountry of Origin in injector mold	
			Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Date Code, Lot Traceability O = Pin 1 indicator Bottom Mark Line 1 = Country Code Country of Origin in injector mold Line 2 = Lot Traceability	VYWWNNN O	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark Country of Origin in injector mold	

Atmel					DCHIP	
Lead/Pin/ Bump Count	Package Description	Pre-Change_Mark	ting Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
		XXXXXXXXXX XXXX YYWW#		Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Date Code, MRL (if shown in ABI) ▲ = Pin 1 location Bottom Mark Line 1 = Country of Origin if not in injector mold Country of Origin in injector mold Line 2 = Lot Traceability	XXXXXXXXX XXXX-COO YYWWNNN	Top MarkLine 1= Atmel LogoLine 2 = Device NameLine 3 = Device Information,Country of OriginLine 4 = Lot Traceability• = Pin 1 indicatorBottom MarkNo bottom markCountry of Origin in injector mold
32	PLCC	XXXXXXXX XXXX YYWW#	XXXXX () AAAAAA	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, MRL (if shown in ABI) ▲ = Pin 1 location Bottom Mark Line 1 = Country of Origin if not in injector mold Country of Origin in injector mold Line 2 = Lot Traceability	XXXXXXXXXX XXX-XXXXXXX YYWWNNN	Top MarkLine 1= Atmel LogoLine 2 = Device NameLine 3 = Device Information, Die ID,RevisionLine 4 = Lot Traceability• = Pin 1 indicatorBottom MarkNo bottom markCountry of Origin in injector mold
44	PLCC			Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Date Code, Lot Traceability O = Pin 1 indicator Bottom Mark Line 1 = Country Code Country of Origin in injector mold Line 2 = Lot Traceability		Top MarkLine 1= Atmel LogoLine 2 = Device NameLine 3 = Lot TraceabilityO = Pin 1 indicatorBottom MarkNo bottom markCountry of Origin in injector mold

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.



ochip)	Post-Change_Marking Guidelines (Microchip)
	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark Country of Origin in injector mold
	Top Mark Line 1= Atmel Logo, EDR Line 2 = Silicon Revision Line 3 = Device Name Line 4 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark Country of Origin in injector mold
	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country or Origin Line 4 = Lot Traceability • = Pin 1 indicator Bottom Mark No bottom mark Country of Origin in injector mold

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.



ochip)	Post-Change_Marking Guidelines (Microchip)
Tanananti	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Die ID, Revision Line 4 = Lot Traceability • = Pin 1 indicator Bottom Mark No bottom mark Country of Origin in injector mold
	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Date Code, Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark Country of Origin in injector mold
	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark Country of Origin in injector mold

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.



ochip)	Post-Change_Marking Guidelines (Microchip)
	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country or Origin Line 4 = Lot Traceability Bottom Mark No bottom mark Country of Origin in injector mold
	Top Mark Line 1=Country of Origin Line 2 = Date Code Line 3 = Lot Traceability • = Pin 1 indicator
	Top Mark Line 1= Truncation Code Line 2 = Class Code, Lot Traceability Line 3 = Date Code • = Pin 1 indicator
	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.

Atmel				
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Micr
		Atmel XXXXXXXXXX XX YYWWX X AAAAAA	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark	Atmel XXXXXXXXXX XX YYWW X YYWWNNN O
48	LQFP 7X7 MM	XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	 Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Date Code, MRL (if shown in ABI) ▲ = Pin 1 location Bottom Mark Line 1 = Country of Origin if not in injector mold Line 2 = Lot Traceability 	XXXXXXXXX XXXX-COO XXXXXX YYWWNNN YYWWNNN
		Atmel XXXXXXXXX XXXXXXXX YYWWX X AAAAAA ARM	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM O = Pin 1 indicator Bottom Mark No bottom mark	Atmel XXXXXXXXX XXXXXXXX YYWW X YYWWNNNARM
44	LQFP 10X10 MM	XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Date Code, MRL (if shown in ABI) ▲ = Pin 1 location Bottom Mark Line 1 = Country of Origin if not in injector mold Line 2 = Lot Traceability	XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX

CROCHIP

ochip)	Post-Change_Marking Guidelines (Microchip)
	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark
	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Die ID, Revision Line 5 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark
	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark
	Top MarkLine 1= Atmel LogoLine 2 = Device NameLine 3 = Device Information,Country of OriginLine 4 = Die ID, RevisionLine 5 = Lot Traceability $O = Pin 1$ indicatorBottom MarkNo bottom mark

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.



ochip)	Post-Change_Marking Guidelines (Microchip)
	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Lot Traceability •O = Pin 1 indicator Bottom Mark No bottom mark
	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Lot Traceability •O = Pin 1 indicator Bottom Mark No bottom mark
	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark
	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.

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		Altmel		
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Micro
			Top MarkLine 1= Atmel LogoLine 2 = Device NameLine 3 = Device InformationLine 4 = Date Code, Subcon Code,Design RevisionLine 5 = Lot Traceability, ARMO = Pin 1 indicatorBottom MarkNo bottom mark	Atmel XXXXXXXXXXXXX XXXXXXX YYWW X YYWWNNN ARM
80	LQFP 12X12 MM	Atmel XXXXXXX XXX YYWWX X AAAAAA	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark	Atmel
100	LQFP 14X14 MM	• • XXXXXXXXXX YWW AAAAA	No bottom mark Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Date Code, Lot Traceability O = Pin 1 indicator Bottom Mark Line 1 = Country Code Line 2 = Lot Traceability	
		MICROCHIP XXXXXXXXXXXX XXXXXX YYWWX X AAAAAA ARM	Top MarkLine 1= Microchip LogoLine 2 = Device NameLine 3 = Device InformationLine 4 = Date Code, Subcon Code,Design RevisionLine 5 = Lot Traceability, ARMO = Pin 1 indicatorBottom MarkNo bottom mark	MICROCHIP XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX

CROCHIP

rochip)	Post-Change_Marking Guidelines (Microchip)
	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM O = Pin 1 indicator Bottom Mark No bottom mark
	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark
	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark
	Top Mark Line 1= Microchip Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM O = Pin 1 indicator Bottom Mark No bottom mark

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.



ochip)	Post-Change_Marking Guidelines (Microchip)
	Top Mark Line 1= Microchip Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM O = Pin 1 indicator Bottom Mark No bottom mark
	OR Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM O = Pin 1 indicator Bottom Mark No bottom mark
	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM O = Pin 1 indicator Bottom Mark No bottom mark
	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.



ochip)	Post-Change_Marking Guidelines (Microchip)
	Top Mark Line 1= Microchip Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM O = Pin 1 indicator Bottom Mark No bottom mark
3	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM O = Pin 1 indicator Bottom Mark No bottom mark
	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM O = Pin 1 indicator Bottom Mark No bottom mark
	Top Mark Line 1= Microchip Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM O = Pin 1 indicator Bottom Mark No bottom mark

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.



ochip)	Post-Change_Marking Guidelines (Microchip)
	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM O = Pin 1 indicator
	No bottom mark
	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Date Code, Design Revision Line 4 = Lot Traceability, ARM O = Pin 1 indicator
	Bottom Mark No bottom mark
	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Lot Traceability O = Pin 1 indicator
	Bottom Mark No bottom mark
	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 3 = Date Code, Design Revision Line 4 = Lot Traceability, ARM O = Pin 1 indicator
\bigcirc	Bottom Mark No bottom mark

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.



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ochip)	Post-Change_Marking Guidelines (Microchip)
	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark
	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark
	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM O = Pin 1 indicator Bottom Mark No bottom mar
	Top Mark Line 1= Atmel Line 2 = Device Name Line 3 = Device Information, Date Code Line 4 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.



ochip)	Post-Change_Marking Guidelines (Microchip)
	Top Mark Line 1= SINOWEL Line 2 = Device Name Line 3 = Device Information, Date Code Line 4 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark
	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Die ID, Revision Line 5 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark
	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark
	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Die ID, Revision Line 5 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.



ochip)	Post-Change_Marking Guidelines (Microchip)
	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark
	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Lot Traceability •O = Pin 1 indicator Bottom Mark No bottom mark
	Top MarkLine 1= Atmel LogoLine 2 = Device NameLine 3 = Device Information,Country of OriginLine 4 = Die ID, RevisionLine 5 = Lot Traceability $O = Pin 1$ indicatorBottom MarkNo bottom mark
	Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Die ID, Revision Line 5 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.



Post-Change_Marking Guidelines (Microchip)
Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark
Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Die ID, Revision Line 5 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark
Top Mark Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Die ID, Revision Line 5 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark



CROCHIP		
ochip)	Post-Change_Marking Guidelines (Microchip)	
	Top Mark Line 1= Atmel Logo Line 2 = Lot Traceability O = Pin 1 indicator	
	Bottom Mark Line 1 = Country Code Line 2 = Lot Traceability	